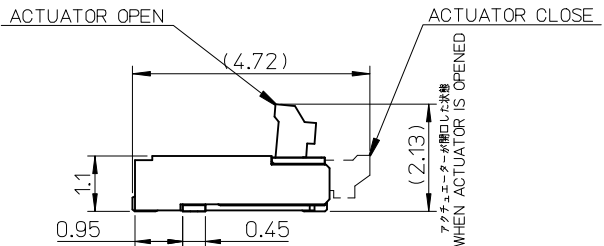
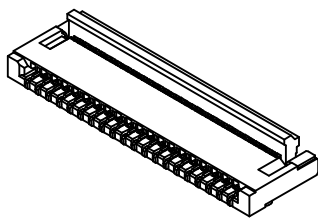


SECTION A-A SECTION B-B



部品構成  
PART COMPOSITION

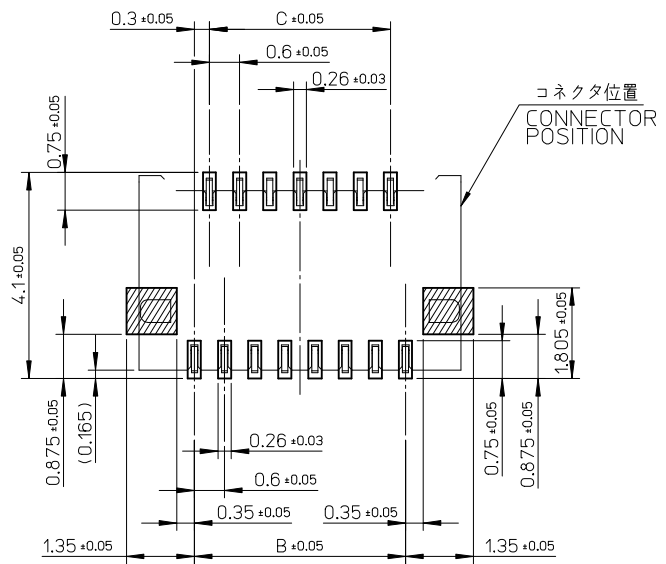
- ハウジング: 液晶ポリマー (LCP)、  
ガラス充填、UL94 V-0、ナチュラル(白)  
HOUSING: LIQUID CRYSTAL POLYMER (LCP),  
GLASS FILLED, UL94 V-0, NATURAL (WHITE)
- 奇数ターミナル: 銅合金  
ODD TERMINAL: COPPER ALLOY  
処理: ニッケル下地 部分金メッキ ニッケルストライプ(バリア)  
FINISH: PARTLY GOLD  
OVER NICKEL PLATING  
NI STRIPE (BARRIER)
- 偶数ターミナル: 銅合金  
EVEN TERMINAL: COPPER ALLOY  
処理: ニッケル下地 部分金メッキ ニッケルストライプ(バリア)  
FINISH: PARTLY GOLD  
OVER NICKEL PLATING  
NI STRIPE (BARRIER)
- アクチュエータ: 材質: ポリアミド(PA) 黒色 UL94V-0  
ACTUATOR  
MATERIAL: POLYAMIDE(PA)  
BLACK UL94-V0
- ネイル: 材質: 磷青銅  
NAIL MATERIAL: PHOSPHOR BRONZE  
処理: ニッケル下地 すすずめつき  
FINISH: TIN OVER NICKEL PLATING
- ELV及びRoHS適合品  
ELV & RoHS COMPLIANT



斜視図  
SCALE 5:1

6	4.8	5.4	7.6	502350-1900	19
4.8	3.6	4.2	6.4	502350-1500	15
D	C	B	A	EMBOSSED PACKAGE	極数
				オーダー番号 ORDER NO.	CIRCUITS
CONNECTOR SERIES No. 502350-**09					

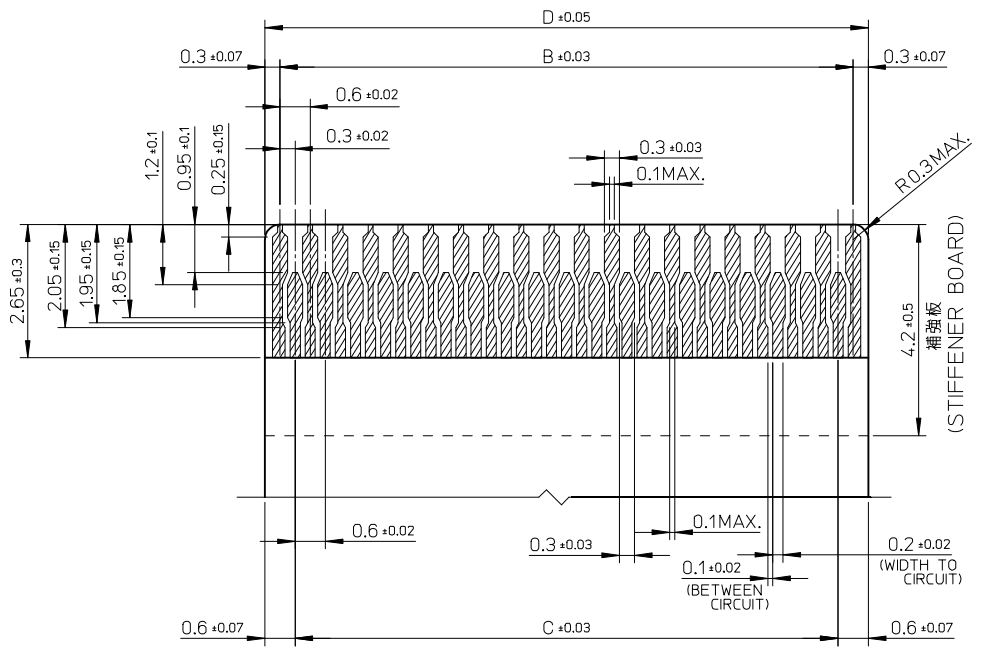
REVISED EC NO: J2014-0958 DRWN: AYOSHI I 2013/12/09 CHKD: YKOBAYASHI 02 2013/12/09 APPR: YNOGAWA 2013/12/25	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± 0.2	DRAWN BY T. HIRAYAMA	DATE 2009/01/05	TITLE 0.3 FPC CONN. E/O H=1.1 HOUSING ASSY WITH GUIDE		
	10 OVER 30 UNDER	± 0.25	CHECKED BY N. MATSUURA	DATE 2009/01/05	MATERIAL NO. SEE CHART		
	30 OVER	± 0.3	APPROVED BY KMORIKAWA	DATE 2010/10/25	DOCUMENT NO. SD-502350-001	SHEET NO. 1 OF 2	
D	DESCRIPTION ANGULAR ±3 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



参考基板レイアウト (マウント面)

P.C. BOARD PATTERN DIM. (REF.)

推奨メタルマスク厚さ : 0.1mm  
 RECOMMENDED METAL MASK THICKNESS : 0.1mm  
 推奨開口率 : 100%  
 APERTURE RATE : 100%

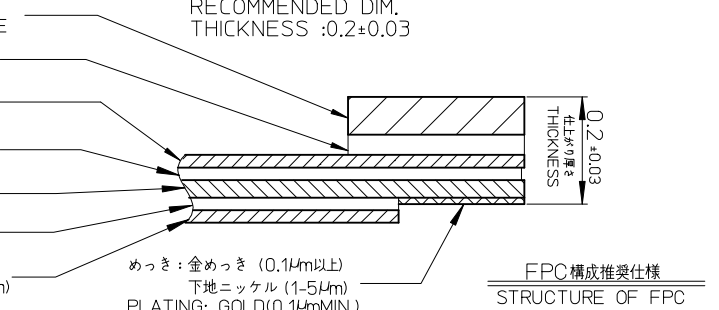


適合FPC推奨寸法

仕上がり厚さ : 0.2±0.03  
 APPLY FPC  
 RECOMMENDED DIM.  
 THICKNESS : 0.2±0.03

補強板 : ポリイミド  
 REINFORCE BOARD: POLYIMIDE  
 熱硬化接着剤  
 THERMOSETTING ADHESIVE  
 ベースフィルム : ポリイミド (25μm)  
 BASE FILM: POLYIMIDE (25μm)  
 熱硬化接着剤  
 THERMOSETTING ADHESIVE  
 導体部 : 銅箔 (35μm)  
 COPPER FOIL (35μm)  
 熱硬化接着剤  
 THERMOSETTING ADHESIVE  
 カバーレイ : ポリイミド (25μm)  
 COVER FILM: POLYIMIDE (25μm)

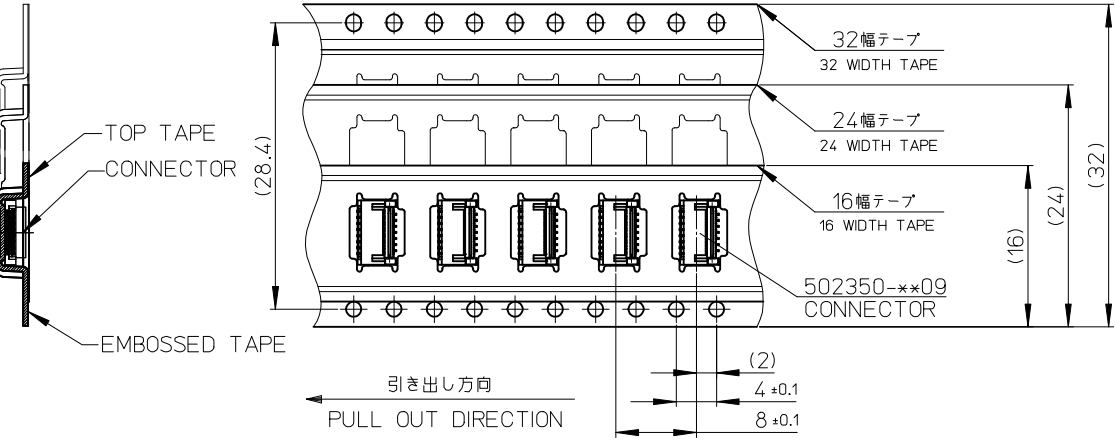
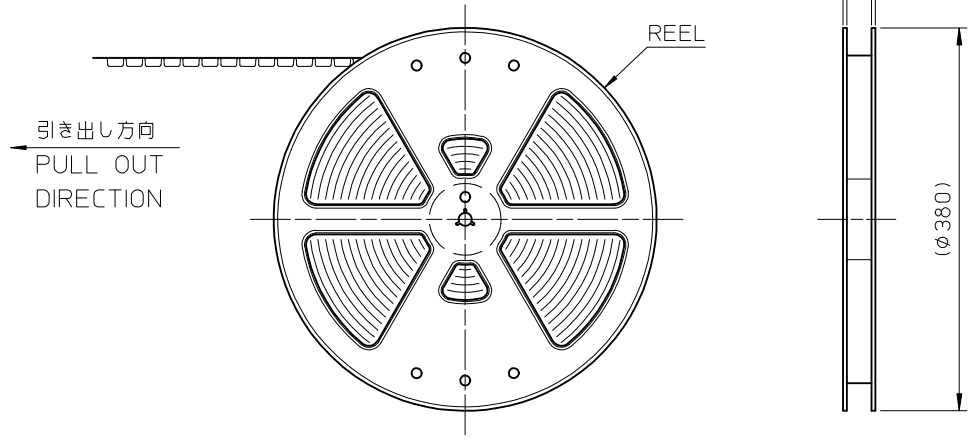
めっき : 金めっき (0.1μm以上)  
 下地ニッケル (1-5μm)  
 PLATING: GOLD (0.1μmMIN.)  
 NICKEL UNDER (1-5μm)



注記 NOTE

- 基板実装前にアクチュエータを操作しないで下さい。  
PLEASE DO NOT OPERATE THE ACTUATOR BEFORE MOUNTING.
- 必ず基板に実装してからアクチュエータを操作して下さい。  
PLEASE OPERATE THE ACTUATOR AFTER MOUNTING ON THE SUBSTRATE.
- FPCについて ABOUT FPC  
補強フィルム材質はポリイミドを推奨します。ベースフィルムは25μmを推奨します。  
接着剤は熱硬化接着剤を推奨します。  
尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様、お願い致します。  
RECOMMENDED STIFFENER MATERIAL: POLYIMIDE  
RECOMMENDED BASE FILM THICKNESS: 25 MICROMETER  
RECOMMENDED ADHESIVE: THERMOSETTING ADHESIVE  
NOTE: PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND BECAUSE THERE IS A POSSIBILITY THAT THE EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.  
打抜き方向は導体側から補強板側を推奨致します。  
導体部については軟銅箔35μmまたは50μmを推奨致します。  
RECOMMENDED PUNCHER DIRECTION: FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.  
RECOMMENDED CONDUCTOR SPECIFICATION: THICKNESS OF SOFT COPPER FOIL: 35MICROMETER OR 50 MICROMETER
- 平坦度は0.1以下  
COPLANARITY TO BE 0.1 MAXIMUM

REVISED EC NO: J2014-0958 DRWN:AYOSHI 101 2013/12/09 CHKD:YKOBAYASHI 022013/12/09 APPR:YNOGAWA 2013/12/25	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
		10 UNDER	± 0.2	MM ONLY		10:1	METRIC	◎ □	
D	REV	10 OVER 30 UNDER	± 0.25	DRAWN BY	DATE	TITLE			
		30 OVER	± 0.3	T. HIRAYAMA	2009/01/05	0.3 FPC CONN. E/O H=1.1 HOUSING ASSY WITH GUIDE			
ANGULAR ± 3 °			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		CHECKED BY	DATE	APPROVED BY		
ANGULAR ± 3 °			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		N. MATSUURA	2009/01/05	DATE		
ANGULAR ± 3 °			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY	DATE	MATERIAL NO.		
ANGULAR ± 3 °			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		KMORI KAWA	2010/10/25	DOCUMENT NO.		
ANGULAR ± 3 °			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART 1		SD-502350-001		
ANGULAR ± 3 °			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		



エンボステープ内の製品の向き  
DIRECTION OF CONNECTOR IN  
EMBOSSED TAPE

**NOTES**

- 製品 (502350-\*\*\*09) の詳細寸法については、図面 SD-502350-001をご参照下さい。  
IN THE PACKAGE, PART NO. 502350-\*\*\*09 DETAILED DIMENSIONS.  
REFER TO SALES DRAWING NO. SD-502350-001.
  - 梱包数量 : 3000 個/リール  
NUMBER OF CONNECTORS : 3000 PCS/REEL
  - リードテープ長さ  
LEAD TAPE LENGTH
- 
- 材料  
キャリアテープ : ポリスチレン (PS)  
トップテープ : PET, OTHER  
リール : ポリスチレン (PS) <リサイクル材を含む>  
MATERIAL  
CARRIER TAPE : POLYSTYRENE(PS)  
TOP TAPE : PET, OTHER  
REEL : POLYSTYRENE(PS)  
<RECYCLE MATERIAL CONTAINED>
  - ELV及びRoHS適合品  
ELV AND RoHS COMPLIANT
  - トップテープの剥離強度については、IEC60286-3に準拠  
Top tape peel force is defined by IEC60286-3.

29.4	25.4	24	502350-1900	19
21.4	17.4	16	502350-1500	15
B	A	WIDTH TAPE	EMBOSSED PACKAGE オーダー番号 ORDER NO.	CIRCUIT

REVISED EC NO: J2014-0958 DRWN: YOSHI I 01 2013/12/10 CHKD: YKOBAYASHI 02 2013/12/10 APPR: YNOGAWA 2013/12/25	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	MODEL NO.	
	10 UNDER	±0.2	DRAWN BY T. HIRAYAMA	DATE 2009/01/05	TITLE 0.3 FPC CONN. H=1.1 EMBSTP PKG			
	10 OVER 30 UNDER	±0.25	CHECKED BY N. MATSUURA	DATE 2009/01/05	molex			
	30 OVER	±0.3	APPROVED BY KMORIKAWA	DATE 2010/10/25				
ANGULAR ±3 °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-502350-002		1 OF 1		
		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				